

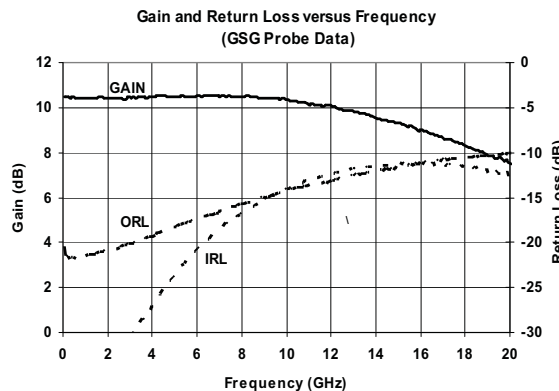


### Product Description

RFMD's SUF-1000 is a monolithically matched high IP<sub>3</sub> broadband pHEMT MMIC amplifier. The self-biased direct-coupled topology provides exceptional cascadable performance from DC to 20GHz. Its efficient operation from a single 5V supply and its compact size (0.88mm x 0.75mm) make it ideal for high-density multi-chip module applications. It is well suited for wideband instrumentation and direct-conversion systems.

#### Optimum Technology Matching® Applied

- GaAs HBT
- GaAs MESFET
- InGaP HBT
- SiGe BiCMOS
- Si BiCMOS
- SiGe HBT
- GaAs pHEMT
- Si CMOS
- Si BJT
- GaN HEMT
- InP HBT
- RF MEMS
- LDMOS



### Features

- Broadband Flat Gain = 10dB
- P1dB = 14dBm
- Direct-Coupled Topology
- Efficient Single-Supply Operation: 5V, 45mA
- Low Gain Variation versus Temperature
- Compact Die Size (0.75mm x 0.88mm)
- Patented Self-Bias Darlington

### Applications

- Ultra-Broadband Communications
- Test Instrumentation
- Military and Space
- LO and IF Mixer Applications
- Replaces Traditional Dual-Supply Distributed Amplifiers

| Parameter                                 | Specification |       |      | Unit  | Condition             |
|---|---------------|-------|------|-------|-----------------------|
|   | Min.          | Typ.  | Max. |       |                       |
| Small Signal Power Gain                   |               | 10.5  |      | dB    | 2GHz and 6GHz         |
|   |               | 9.0   |      | dB    | 16GHz                 |
| Output Power at 1dB Compression           |               | 14.0  |      | dBm   | 2GHz, 6GHz, and 16GHz |
| Output Third Order Intercept Point        |               | 26.0  |      | dBm   | 2GHz and 6GHz         |
|   |               | 25.5  |      | dBm   | 16GHz                 |
| Noise Figure                              |               | 4.5   |      | dB    | 2GHz and 6GHz         |
|   |               | 5.0   |      | dB    | 16GHz                 |
| Input Return Loss                         |               | -37.0 |      | dB    | 2GHz                  |
|   |               | -20.5 |      | dB    | 6GHz                  |
|   |               | -11.5 |      | dB    | 16GHz                 |
| Output Return Loss                        |               | -21.5 |      | dB    | 2GHz                  |
|   |               | -17.5 |      | dB    | 6GHz                  |
|   |               | -11.0 |      | dB    | 16GHz                 |
| Reverse Isolation                         |               | -21.0 |      | dB    | 2GHz                  |
|   |               | -17.5 |      | dB    | 6GHz                  |
|   |               | -17.0 |      | dB    | 16GHz                 |
| Device Operating Voltage                  |               | 3.4   |      | V     |                       |
| Device Operating Current                  |               | 46    |      | mA    |                       |
| Gain Variation vs. Temperature            |               | -0.01 |      | dB/°C |                       |
| Thermal Resistance (junction to backside) |               | 262   |      | °C/W  |                       |

Test Conditions: V = 5.0V R<sub>BIAS</sub> = 35Ω, I<sub>D</sub> = 46mA, OIP<sub>3</sub> Tone Spacing = 1MHz, P<sub>OUT</sub> per tone = 0dBmZ<sub>S</sub> = Z<sub>L</sub> = 50Ω, 25 °C, GSG Probe Data with Bias Tees

## Absolute Maximum Ratings

| Parameter                             | Rating      | Unit |
|---------------------------------------|-------------|------|
| Max Device Current ( $I_D$ )          | 70          | mA   |
| Max Device Voltage ( $V_D$ )          | 4           | V    |
| Max RF Input Power                    | 20          | dBm  |
| Max Dissipated Power                  | 280         | mW   |
| Max Junction Temperature ( $T_J$ )    | 150         | °C   |
| Operating Temperature Range ( $T_L$ ) | -40 to + 85 | °C   |
| Max Storage Temperature               | -65 to +150 | °C   |
| Human Body Model                      | Class 1A    |      |



**Caution!** ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

The information in this publication is believed to be accurate and reliable. However, no responsibility is assumed by RF Micro Devices, Inc. ("RFMD") for its use, nor for any infringement of patents, or other rights of third parties, resulting from its use. No license is granted by implication or otherwise under any patent or patent rights of RFMD. RFMD reserves the right to change component circuitry, recommended application circuitry and specifications at any time without prior notice.



RFMD Green: RoHS compliant per EU Directive 2002/95/EC, halogen free per IEC 61249-2-21, < 1000ppm each of antimony trioxide in polymeric materials and red phosphorus as a flame retardant, and <2% antimony in solder

Operation of this device beyond any one of these limits may cause permanent damage. For reliable continuous operation, the device voltage and current must not exceed the maximum operating values specified in the table on page one.

Bias Conditions should also satisfy the following expression:

$$I_D V_D < (T_J - T_L) / R_{TH}, \text{ J-I and } T_L = \text{Backside of die}$$

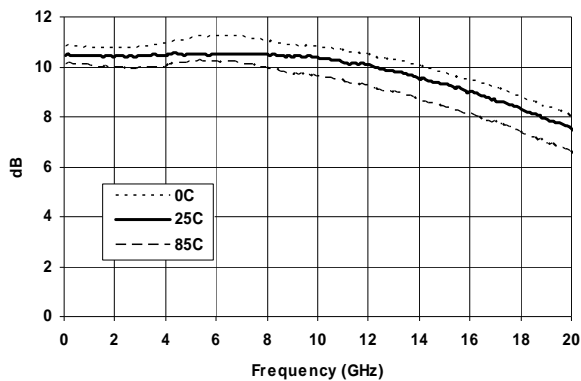
## Typical Performance (GSG Probe Data)

| Freq (GHz) | VD (V) | Current (mA) | Gain (dB) | P1dB (dBm) | OIP3 (dBm) | S11 (dB) | S22 (dB) | NF (dB) |
|------------|--------|--------------|-----------|------------|------------|----------|----------|---------|
| 0.10       | 3.4    | 46.0         | 10.4      |            |            | -34.0    | -21.0    |         |
| 0.50       | 3.4    | 46.0         | 10.4      |            |            | -36.0    | -22.0    |         |
| 0.85       | 3.4    | 46.0         | 10.4      | 13.0       | 24.5       | -37.0    | -22.0    | 4.4     |
| 2.00       | 3.4    | 46.0         | 10.4      | 14.0       | 26.0       | -34.0    | -21.0    | 4.4     |
| 4.00       | 3.4    | 46.0         | 10.5      | 13.5       | 26.0       | -26.0    | -19.0    | 4.4     |
| 6.00       | 3.4    | 46.0         | 10.5      | 14.0       | 26.0       | -20.0    | -17.0    | 4.6     |
| 10.00      | 3.4    | 46.0         | 10.3      | 14.0       | 25.0       | -14.0    | -14.0    | 4.7     |
| 16.00      | 3.4    | 46.0         | 9.0       | 14.0       | 25.5       | -12.0    | -11.0    | 5.1     |
| 20.00      | 3.4    | 46.0         | 7.6       |            |            | -13.0    | -10.0    | 5.1     |

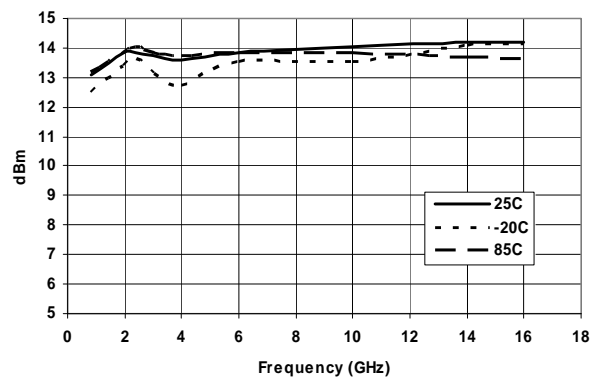
Test Conditions: GSG Probe Data With Bias Tees,  $R_{BIAS} = 35\Omega$  OIP<sub>3</sub> Tone Spacing = 1MHz,  $P_{OUT}$  per tone = 0dBm, 25°C

## Typical Performance

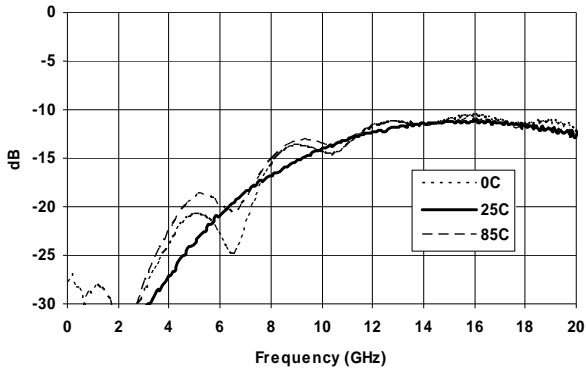
S21 vs. Frequency



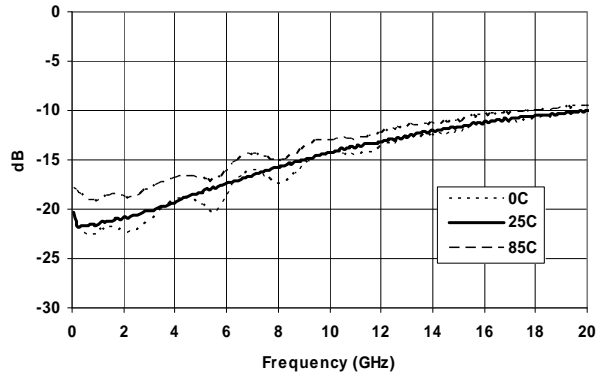
P1dB vs. Frequency



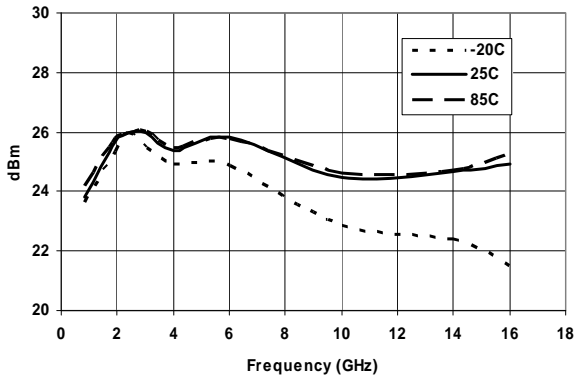
**S11 vs. Frequency**



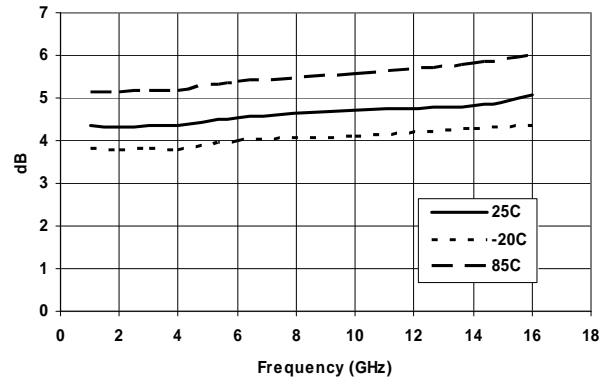
**S22 vs. Frequency**



**OIP3 vs. Frequency**

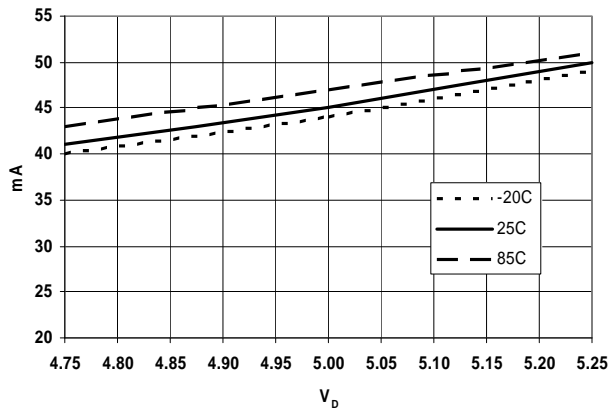


**Noise Figure vs. Frequency**



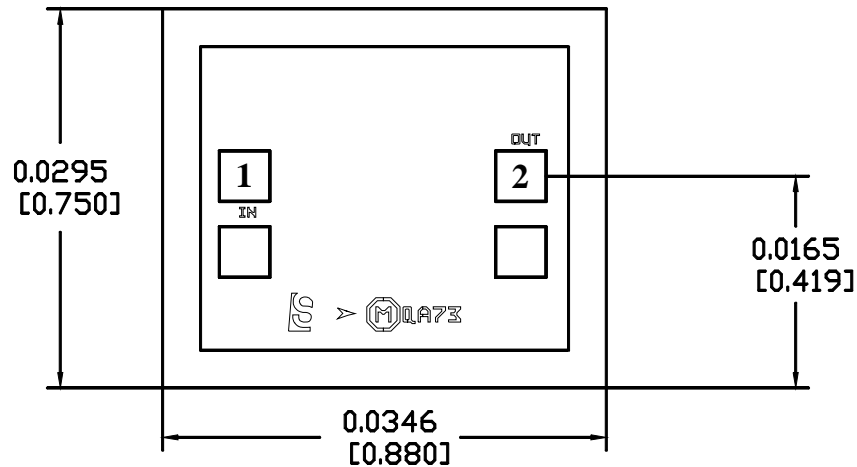
**Current Variation Versus Temperature**

**Current vs. Voltage**



| Pin        | Function   | Description  |
|------------|------------|--|
| 1          | RFIN       | This pad is DC coupled and matched to 50Ω. An external DC block is required. |
| 2          | RFOUT/BIAS | This pad is DC coupled and matched to 50Ω. Bias is applied through this pad. |
| Die Bottom | GND        | Die bottom must be connected to RF/DC ground using silver-filled epoxy.      |

## Pad Description



### Notes:

1. All dimensions in inches (millimeters).
2. No connection required for unlabeled bond pads.
3. Die thickness is 0.004 [0.10]
4. Typical bond pad is 0.004 [0.10] square.
5. Backside metalization: Gold.
6. Backside is ground.
7. Bond pad metalization: Gold.

Device Assembly

